

# 128Mbit SDRAM

*8M x 4Bit x 4 Banks*  
*Synchronous DRAM*  
*LVTTL*

Revision 0.0

Aug. 1999

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## CMOS SDRAM

## FEATURES

- ## GENERAL DESCRIPTION

## ORDERING INFORMATION

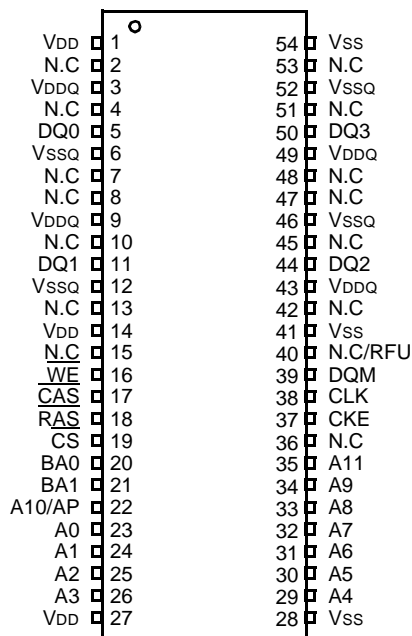
Part No.	Max Freq.	Interface	Package
K4S280432A-TC/L75	133MHz(CL=3)	LVTTTL	54 TSOP(II)
K4S280432A-TC/L80	125MHz(CL=3)		
K4S280432A-TC/L1H	100MHz(CL=2)		
K4S280432A-TC/L1L	100MHz(CL=3)		
K4S280432A-TC/L10	66MHz(CL=2 &3)		

The diagram illustrates the functional blocks of the memory array and control logic. At the bottom, a **Timing Register** receives external signals: **CLK**, **CKE**, **CS**, **RAS**, **CAS**, **WE**, **DQM**, and **LDQM**. It outputs control signals: **LRAS**, **LCBR**, **LWE**, **LCAS**, **LWCBR**, and **LDQM**. The **Address Register** receives **CLK** and **ADD** signals. It outputs to the **Bank Select** block and the **Row Buffer Refresh Counter**. The **Row Buffer Refresh Counter** also receives **LRAS** and **LCBR** signals. The **Bank Select** block outputs to the **Row Decoder**. The **Row Decoder** outputs to four **8M x 4** memory banks, which are connected to a **Sense AMP**. The **Col. Buffer** receives **LCAS** and outputs to a **Column Decoder**, which is connected to the **Sense AMP**. The **Latency & Burst Length** block receives **LWCBR** and outputs to the **Output Buffer**. The **Programming Register** outputs to the **Latency & Burst Length** block. The **Data Input Register** receives data from the **I/O Control** block and outputs to the memory banks. The **I/O Control** block receives **LWE** and **LDQM** signals and outputs **DQi** to the **Output Buffer**. The **Output Buffer** outputs **DQi** to the **I/O Control** block.



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## PIN CONFIGURATION (Top view)



54Pin TSOP (II)  
(400mil x 875mil)  
(0.8 mm Pin pitch)

## PIN FUNCTION DESCRIPTION

Pin	Name	Input Function
CLK	System clock	Active on the positive going edge to sample all inputs.
$\overline{CS}$	Chip select	Disables or enables device operation by masking or enabling all inputs except CLK, CKE and DQM
CKE	Clock enable	Masks system clock to freeze operation from the next clock cycle. CKE should be enabled at least one cycle prior to new command. Disable input buffers for power down in standby.
A <sub>0</sub> ~ A <sub>11</sub>	Address	Row/column addresses are multiplexed on the same pins. Row address : RA <sub>0</sub> ~ RA <sub>11</sub> , Column address : CA <sub>0</sub> ~ CA <sub>9</sub> , CA <sub>11</sub>
BA <sub>0</sub> ~ BA <sub>1</sub>	Bank select address	Selects bank to be activated during row address latch time. Selects bank for read/write during column address latch time.
$\overline{RAS}$	Row address strobe	Latches row addresses on the positive going edge of the CLK with $\overline{RAS}$ low. Enables row access & precharge.
$\overline{CAS}$	Column address strobe	Latches column addresses on the positive going edge of the CLK with $\overline{CAS}$ low. Enables column access.
$\overline{WE}$	Write enable	Enables write operation and row precharge. Latches data in starting from $\overline{CAS}$ , $\overline{WE}$ active.
DQM	Data input/output mask	Makes data output Hi-Z, t <sub>SHZ</sub> after the clock and masks the output. Blocks data input when DQM active.
DQ <sub>0</sub> ~ 3	Data input/output	Data inputs/outputs are multiplexed on the same pins.
VDD/VSS	Power supply/ground	Power and ground for the input buffers and the core logic.
VDDQ/VSSQ	Data output power/ground	Isolated power supply and ground for the output buffers to provide improved noise immunity.
N.C/RFU	No connection /reserved for future use	This pin is recommended to be left No Connection on the device.

**ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Value	Unit
Voltage on any pin relative to Vss	V <sub>IN</sub> , V <sub>OUT</sub>	-1.0 ~ 4.6	V
Voltage on VDD supply relative to Vss	VDD, VDDQ	-1.0 ~ 4.6	V
Storage temperature	T <sub>STG</sub>	-55 ~ +150	°C
Power dissipation	P <sub>D</sub>	1	W
Short circuit current	I <sub>OS</sub>	50	mA

**Note :** Permanent device damage may occur if "ABSOLUTE MAXIMUM RATINGS" are exceeded.  
Functional operation should be restricted to recommended operating condition.  
Exposure to higher than recommended voltage for extended periods of time could affect device reliability.

**DC OPERATING CONDITIONS**

Recommended operating conditions (voltage referenced to Vss = 0V, T<sub>A</sub> = 0 to 70°C)

Parameter	Symbol	Min	Typ	Max	Unit	Note
Supply voltage	VDD, VDDQ	3.0	3.3	3.6	V	
Input logic high voltage	V <sub>IH</sub>	2.0	3.0	VDD+0.3	V	1
Input logic low voltage	V <sub>IL</sub>	-0.3	0	0.8	V	2
Output logic high voltage	V <sub>OH</sub>	2.4	-	-	V	I <sub>OH</sub> = -2mA
Output logic low voltage	V <sub>OL</sub>	-	-	0.4	V	I <sub>OL</sub> = 2mA
Input leakage current	I <sub>LI</sub>	-10	-	10	uA	3

**Notes :** 1. V<sub>IH</sub> (max) = 5.6V AC. The overshoot voltage duration is ≤ 3ns.  
2. V<sub>IL</sub> (min) = -2.0V AC. The undershoot voltage duration is ≤ 3ns.  
3. Any input 0V ≤ V<sub>IN</sub> ≤ VDDQ,  
Input leakage currents include Hi-Z output leakage for all bi-directional buffers with Tri-State outputs.

**CAPACITANCE** (VDD = 3.3V, T<sub>A</sub> = 23°C, f = 1MHz, VREF = 1.4V ± 200 mV)

Pin	Symbol	Min	Max	Unit	Note
Clock	CCLK	2.5	4.0	pF	1
RAS, CAS, WE, CS, CKE, DQM	CIN	2.5	5.0	pF	2
Address	CADD	2.5	5.0	pF	2
DQ0 ~ DQ3	COUT	4.0	6.5	pF	3

**Notes :** 1. -75 only specify a maximum value of 3.5pF  
2. -75 only specify a maximum value of 3.8pF  
3. -75 only specify a maximum value of 6.0pF

## DC CHARACTERISTICS

(Recommended operating condition unless otherwise noted,  $T_A = 0$  to  $70^\circ\text{C}$ )

Parameter	Symbol	Test Condition		Version					Unit	Note
				-75	-80	-1H	-1L	-10		
Operating current (One bank active)	Icc1	Burst length = 1 trc ≥ trc(min) Io = 0 mA		120	120	110	110	110	mA	1
Precharge standby current in power-down mode	Icc2P	CKE ≤ VIL(max), tcc = 10ns		1					mA	
	Icc2PS	CKE & CLK ≤ VIL(max), tcc = ∞		1						
Precharge standby current in non power-down mode	Icc2N	CKE ≥ VIH(min), CS ≥ VIH(min), tcc = 10ns Input signals are changed one time during 20ns		20					mA	
	Icc2NS	CKE ≥ VIH(min), CLK ≤ VIL(max), tcc = ∞ Input signals are stable		7						
Active standby current in power-down mode	Icc3P	CKE ≤ VIL(max), tcc = 10ns		5					mA	
	Icc3PS	CKE & CLK ≤ VIL(max), tcc = ∞		5						
Active standby current in non power-down mode (One bank active)	Icc3N	CKE ≥ VIH(min), CS ≥ VIH(min), tcc = 10ns Input signals are changed one time during 20ns		30					mA	
	Icc3NS	CKE ≥ VIH(min), CLK ≤ VIL(max), tcc = ∞ Input signals are stable		20					mA	
Operating current (Burst mode)	Icc4	Io = 0 mA Page burst 4Banks Activated tccd = 2CLKs		140	135	115	115	115	mA	1
Refresh current	Icc5	trc ≥ trc(min)		220	220	210	210	210	mA	2
Self refresh current	Icc6	CKE ≤ 0.2V	C	1.5					mA	3
			L	800					uA	4

**Notes :** 1. Measured with outputs open.

2. Refresh period is 64ms.

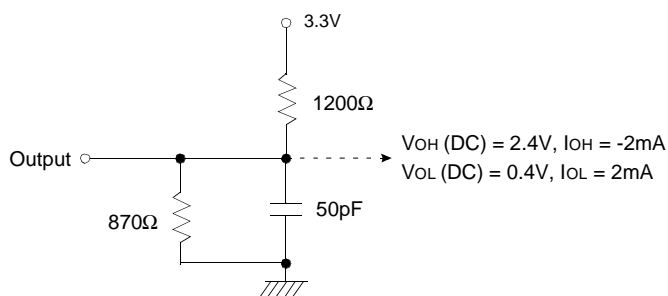
3. K4S280432A-TC\*\*

4. K4S280432A-TL\*\*

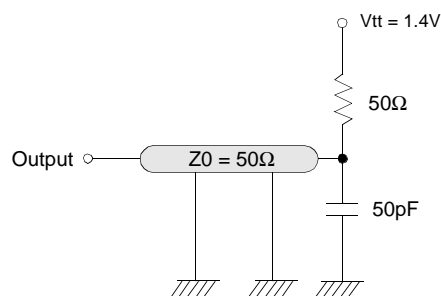
5. Unless otherwise noted, input swing level is CMOS( $V_{IH}/V_{IL} = V_{DDQ}/V_{SSQ}$ )

**AC OPERATING TEST CONDITIONS** ( $V_{DD} = 3.3V \pm 0.3V$ ,  $T_A = 0$  to  $70^\circ\text{C}$ )

Parameter	Value	Unit
Input levels ( $V_{ih}/V_{il}$ )	2.4/0.4	V
Input timing measurement reference level	1.4	V
Input rise and fall time	$t_r/t_f = 1/1$	ns
Output timing measurement reference level	1.4	V
Output load condition	See Fig. 2	



(Fig. 1) DC output load circuit



(Fig. 2) AC output load circuit

**OPERATING AC PARAMETER**

(AC operating conditions unless otherwise noted)

Parameter		Symbol	Version					Unit	Note
			- 75	- 80	- 1H	- 1L	-10		
Row active to row active delay		tRRD(min)	15	16	20	20	20	ns	1
RAS to CAS delay		tRCD(min)	20	20	20	20	24	ns	1
Row precharge time		tRP(min)	20	20	20	20	24	ns	1
Row active time		tRAS(min)	45	48	50	50	50	ns	1
		tRAS(max)	100					us	
Row cycle time		tRC(min)	65	68	70	70	80	ns	1
Last data in to row precharge		tRDL(min)	2					CLK	2,5
Last data in to Active delay		tDAL(min)	2 CLK + 20 ns					-	5
Last data in to new col. address delay		tCDL(min)	1					CLK	2
Last data in to burst stop		tBDL(min)	1					CLK	2
Col. address to col. address delay		tCCD(min)	1					CLK	3
Number of valid output data	CAS latency=3		2					ea	4
	CAS latency=2		-		1				

**Notes :** 1. The minimum number of clock cycles is determined by dividing the minimum time required with clock cycle time and then rounding off to the next higher integer.

2. Minimum delay is required to complete write.

3. All parts allow every cycle column address change.

4. In case of row precharge interrupt, auto precharge and read burst stop.

5. For -80/1H/1L/10,  $t_{RDL}=1\text{CLK}$  and  $t_{DAL}=1\text{CLK}+20\text{ns}$  is also supported .

SAMSUNG recommends  $t_{RDL}=2\text{CLK}$  and  $t_{DAL}=2\text{CLK} + 20\text{ns}$ .

**AC CHARACTERISTICS** (AC operating conditions unless otherwise noted)

Parameter		Symbol	- 75		- 80		- 1H		- 1L		- 10		Unit	Note
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
CLK cycle time	CAS latency=3	tcc	7.5	1000	8	1000	10	1000	10	1000	10	1000	ns	1
	CAS latency=2		-		-		10		12		13			
CLK to valid output delay	CAS latency=3	tsac		5.4		6		6		6		7	ns	1,2
	CAS latency=2			-		-		6		7		7		
Output data hold time	CAS latency=3	toH	2.7		3		3		3		3		ns	2
	CAS latency=2		-		-		3		3		3			
CLK high pulse width		tCH	2.5		3		3		3		3.5		ns	3
CLK low pulse width		tCL	2.5		3		3		3		3.5		ns	3
Input setup time		tSS	1.5		2		2		2		2.5		ns	3
Input hold time		tSH	0.8		1		1		1		1.5		ns	3
CLK to output in Low-Z		tsLZ	1		1		1		1		1		ns	2
CLK to output in Hi-Z	CAS latency=3	tSHZ		5.4		6		6		6		7	ns	
	CAS latency=2			-		-		6		7		7		

- Notes :**
- Parameters depend on programmed CAS latency.
  - If clock rising time is longer than 1ns, (tr/2-0.5)ns should be added to the parameter.
  - Assumed input rise and fall time (tr & tf) = 1ns.  
If tr & tf is longer than 1ns, transient time compensation should be considered,  
i.e., [(tr + tf)/2-1]ns should be added to the parameter.

**DQ BUFFER OUTPUT DRIVE CHARACTERISTICS**

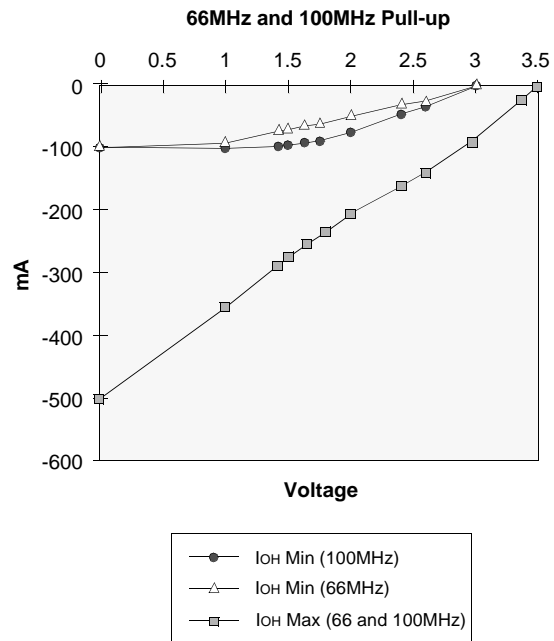
Parameter	Symbol	Condition	Min	Typ	Max	Unit	Notes
Output rise time	trh	Measure in linear region : 1.2V ~ 1.8V	1.37		4.37	Volts/ns	3
Output fall time	tfh	Measure in linear region : 1.2V ~ 1.8V	1.30		3.8	Volts/ns	3
Output rise time	trh	Measure in linear region : 1.2V ~ 1.8V	2.8	3.9	5.6	Volts/ns	1,2
Output fall time	tfh	Measure in linear region : 1.2V ~ 1.8V	2.0	2.9	5.0	Volts/ns	1,2

- Notes :**
- Rise time specification based on 0pF + 50 Ω to Vss, use these values to design to.
  - Fall time specification based on 0pF + 50 Ω to VDD, use these values to design to.
  - Measured into 50pF only, use these values to characterize to.
  - All measurements done with respect to Vss.

## IBIS SPECIFICATION

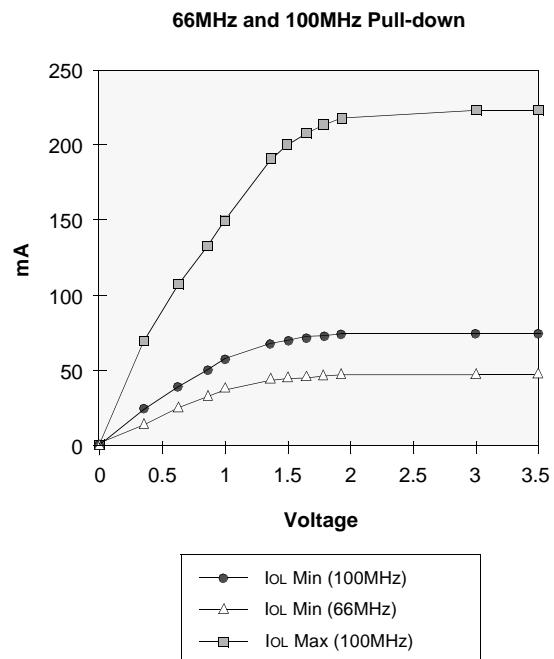
## IOH Characteristics (Pull-up)

Voltage	100MHz Min	100MHz Max	66MHz Min
(V)	I (mA)	I (mA)	I (mA)
3.45		-2.4	
3.3		-27.3	
3.0	0.0	-74.1	-0.7
2.6	-21.1	-129.2	-7.5
2.4	-34.1	-153.3	-13.3
2.0	-58.7	-197.0	-27.5
1.8	-67.3	-226.2	-35.5
1.65	-73.0	-248.0	-41.1
1.5	-77.9	-269.7	-47.9
1.4	-80.8	-284.3	-52.4
1.0	-88.6	-344.5	-72.5
0.0	-93.0	-502.4	-93.0



## IOL Characteristics (Pull-down)

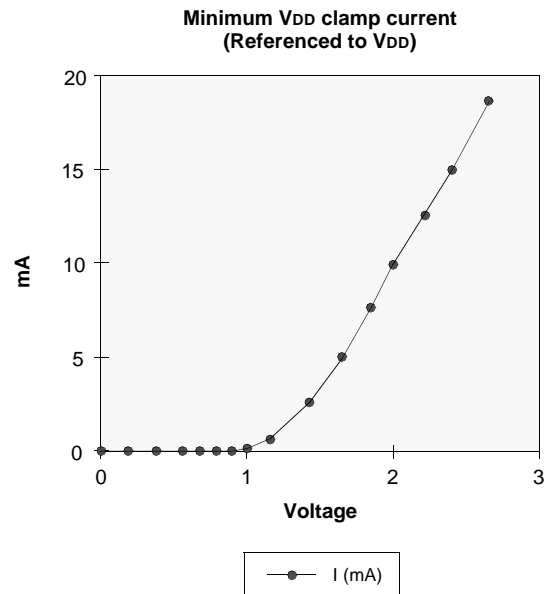
Voltage	100MHz Min	100MHz Max	66MHz Min
(V)	I (mA)	I (mA)	I (mA)
0.0	0.0	0.0	0.0
0.4	27.5	70.2	17.7
0.65	41.8	107.5	26.9
0.85	51.6	133.8	33.3
1.0	58.0	151.2	37.6
1.4	70.7	187.7	46.6
1.5	72.9	194.4	48.0
1.65	75.4	202.5	49.5
1.8	77.0	208.6	50.7
1.95	77.6	212.0	51.5
3.0	80.3	219.6	54.2
3.45	81.4	222.6	54.9



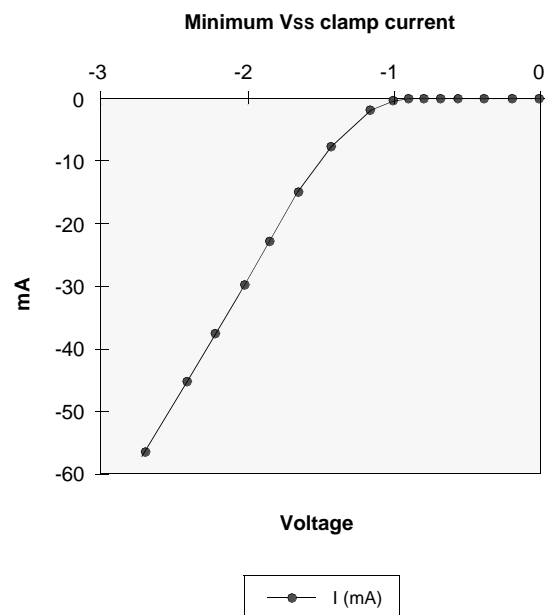


**V<sub>DD</sub> Clamp @ CLK, CKE,  $\overline{\text{CS}}$ , DQM & DQ**

V <sub>DD</sub> (V)	I (mA)
0.0	0.0
0.2	0.0
0.4	0.0
0.6	0.0
0.7	0.0
0.8	0.0
0.9	0.0
1.0	0.23
1.2	1.34
1.4	3.02
1.6	5.06
1.8	7.35
2.0	9.83
2.2	12.48
2.4	15.30
2.6	18.31

**V<sub>SS</sub> Clamp @ CLK, CKE,  $\overline{\text{CS}}$ , DQM & DQ**

V <sub>SS</sub> (V)	I (mA)
-2.6	-57.23
-2.4	-45.77
-2.2	-38.26
-2.0	-31.22
-1.8	-24.58
-1.6	-18.37
-1.4	-12.56
-1.2	-7.57
-1.0	-3.37
-0.9	-1.75
-0.8	-0.58
-0.7	-0.05
-0.6	0.0
-0.4	0.0
-0.2	0.0
0.0	0.0



## SIMPLIFIED TRUTH TABLE

Command			CKEn-1	CKEn	$\overline{CS}$	$\overline{RAS}$	$\overline{CAS}$	$\overline{WE}$	DQM	BA0,1	A10/AP	A11, A9 ~ A0	Note
Register	Mode register set		H	X	L	L	L	L	X	OP code			1,2
Refresh	Auto refresh		H	H	L	L	L	H	X	X			3
	Self refresh	Entry		L									3
		Exit	L	H	L	H	H	H	X	X			3
					H	X	X	X					3
Bank active & row addr.			H	X	L	L	H	H	X	V	Row address		
Read & column address	Auto precharge disable		H	X	L	H	L	H	X	V	L	Column address (A0~A9, A11)	4
	Auto precharge enable										H		4,5
Write & column address	Auto precharge disable		H	X	L	H	L	L	X	V	L	Column address (A0~A9, A11)	4
	Auto precharge enable										H		4,5
Burst stop			H	X	L	H	H	L	X	X			6
Precharge	Bank selection		H	X	L	L	H	L	X	V	L	X	
	All banks									X	H		
Clock suspend or active power down		Entry	H	L	H	X	X	X	X	X			
					L	V	V	V					
		Exit	L	H	X	X	X	X	X				
Precharge power down mode		Entry	H	L	H	X	X	X	X	X			
					L	H	H	H					
		Exit	L	H	H	X	X	X	X				
					L	V	V	V					
DQM			H	X					V	X			7
No operation command			H	X	H	X	X	X	X	X			
					L	H	H	H					

(V=Valid, X=Don't care, H=Logic high, L=Logic low)

**Notes :** 1. OP Code : Operand code

A0 ~ A11 &amp; BA0 ~ BA1 : Program keys. (@ MRS)

2. MRS can be issued only at all banks precharge state.

A new command can be issued after 2 CLK cycles of MRS.

3. Auto refresh functions are as same as CBR refresh of DRAM.

The automatical precharge without row precharge command is meant by "Auto".

Auto/self refresh can be issued only at all banks precharge state.

4. BA0 ~ BA1 : Bank select addresses.

If both BA0 and BA1 are "Low" at read, write, row active and precharge, bank A is selected.

If both BA0 is "Low" and BA1 is "High" at read, write, row active and precharge, bank B is selected.

If both BA0 is "High" and BA1 is "Low" at read, write, row active and precharge, bank C is selected.

If both BA0 and BA1 are "High" at read, write, row active and precharge, bank D is selected.

If A10/AP is "High" at row precharge, BA0 and BA1 is ignored and all banks are selected.

5. During burst read or write with auto precharge, new read/write command can not be issued.

Another bank read/write command can be issued after the end of burst.

New row active of the associated bank can be issued at tRP after the end of burst.

6. Burst stop command is valid at every burst length.

7. DQM sampled at positive going edge of a CLK and masks the data-in at the very CLK (Write DQM latency is 0), but makes Hi-Z state the data-out of 2 CLK cycles after. (Read DQM latency is 2)